



STYCAST[#] 2851 FT

One Component Epoxy Encapsulant With High Thermal Conductivity

Key Feature	Benefit

Product Description :

STYCAST 2851 FT is a highly filled, one component epoxy encapsulant with most of the outstanding properties of STYCAST 2850 FT reached with Catalyst 11. STYCAST 2851 FT contains no solvents, but is 100 % solids and requires no additional weighing step to add a curing agent.

STYCAST 2851 FT can be cured at a temperature as low as 90°C within a few hours to yield a material with high thermal conductivity and low thermal expansion.

Applications :

STYCAST 2851 FT has very good electrical insulation properties and is well suited for providing a protective covering for chips which must withstand pressure cooker testing.

Properties Of Material As Supplied :

Property	Test Method	Unit	Value
Chemistry			epoxy
Appearance	Visual		black
Density	ASTM-D-792	g/cm ³	2,2 - 2,4
Mixed Viscosity at 25°C	ASTM-D-2393	Pa.s	70 - 100
at 45°C	ASTM-D-2393	Pa.s	30 - 35

Cure Schedule :

Please refer to the instructions for use above.

Instructions For Use :

Although STYCAST 2851 FT is a castable system, for applications requiring a lower viscosity, very slight warming will reduce viscosity significantly, e.g. to 45°C. Caution : do not leave the material at a warm temperature any longer than necessary as it will shorten its shelf life considerably.

Mix the entire contents of the shipping container to a uniform consistency each time before removing material. Power mixing is preferred. MOLD RELEASE 122 S will prevent adhesion to molds. When necessary, entrapped air can be removed by vacuum deairing.

For optimum smooth surface, cure temperature should not exceed 110°C. For optimum high temperature performance, post cure 4 hours at 150°C.

Cure at any of the following schedules :

- 5 h at 90°C
- or 2 h at 110°C
- or 1 h at 120°C.

Note

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Americas
+1.888.943.6535

Europe
+44.1442.278.000

Asia
+86.21.3898.4800



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